

April 2000 Revised May 2003

NC7SZ57 • NC7SZ58 TinyLogic® UHS Universal Configurable 2-Input **Logic Gates**

General Description

The NC7SZ57 and the NC7SZ58 are Universal Configurable 2-Input Logic Gates. Each device is capable of being configured for 1 of 5 unique 2-input logic functions. Any possible 2-input combinatorial logic function can be implemented as shown in the Function Selection Table. Device functionality is selected by how the device is wired at the board level. Figure 1 through Figure 10 illustrate how to connect the NC7SZ57 and NC7SZ58 respectively for the desired logic function. All inputs have been implemented with hysteresis.

The device is fabricated with advanced CMOS technology to achieve ultra high speed with high output drive while maintaining low static power dissipation over a broad V_{CC} operating range. The device is specified to operate over the 1.65V to 5.5V V_{CC} operating range. The input and output are high impedance when V_{CC} is 0V. Inputs tolerate voltages up to 5.5V independent of V_{CC} operating range.

Features

- Space saving SC70-6 lead surface mount package
- Ultra small MicroPak™ leadless package
- Ultra High Speed
- Capable of implementing any 2-input logic function
- Typical usage replaces 2 TinyLogic® gate devices
- Reduces part counts in inventory
- Broad V_{CC} operating range: 1.65V to 5.5V
- Power down high impedance input/output
- Overvoltage tolerant inputs facilitate 5V to 3V translation
- Patented noise/EMI reduction circuitry implemented

Ordering Code:

Order Number	Package Number	Product Code Top Mark	Package Description	Supplied As
NC7SZ57P6X	MAA06A	Z57	6-Lead SC70, EIAJ SC88, 1.25mm Wide	3k Units on Tape and Reel
NC7SZ58P6X	MAA06A	Z58	6-Lead SC70, EIAJ SC88, 1.25mm Wide	3k Units on Tape and Reel
NC7SZ57L6X	MAC06A	KK	6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel
NC7SZ58L6X	MAC06A		6-Lead MicroPak, 1.0mm Wide	5k Units on Tape and Reel

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Pin Descriptions

Pin Name	Description
I ₀ , I ₁ , I ₂	Data Inputs
Y	Output

Function Table

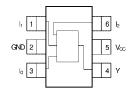
	Inputs		NC7SZ57	NC7SZ58		
l ₂	I ₁	I ₀	$Y = (I_0) \bullet (I_2) + (I_1) \bullet (I_2)$	$Y = (I_0) \bullet (I_2) + (I_1) \bullet (I_2)$		
L	L	L	Н	L		
L	L	Н	L	Н		
L	Н	L	Н	L		
L	Н	Н	L	Н		
Н	L	L	L	Н		
Н	L	Н	L	Н		
Н	Н	L	Н	L		
Н	Н	Η	Н	L		

H = HIGH Logic Level

L = LOW Logic Level

Connection Diagrams

Pin Assignments for SC70



(Top View) NC7SZ57 and NC7SZ58

Pin One Orientation Diagram

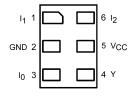


Pin One

AAA = Product Code Top Mark - see ordering code

Note: Orientation of Top Mark determines Pin One location. Read the top product code mark left to right, Pin One is the lower left pin (see diagram).

Pad Assignment for MicroPak



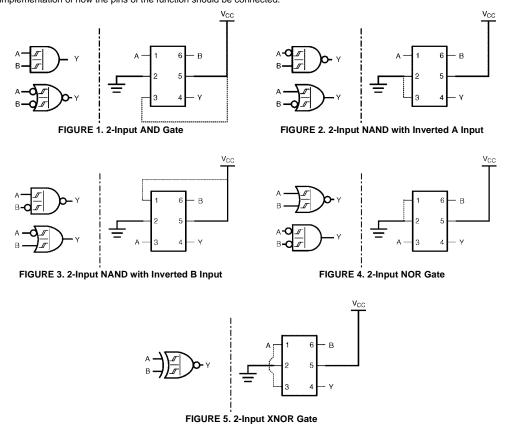
(Top Thru View)

Function Selection Table

2 Innut I agis Function	Device	Connection
2-Input Logic Function	Selection	Configuration
2-Input AND	NC7SZ57	Figure 1
2-Input AND with inverted input	NC7SZ58	Figures 7, 8
2-Input AND with both inputs inverted	NC7SZ57	Figure 4
2-Input NAND	NC7SZ58	Figure 6
2-Input NAND with inverted input	NC7SZ57	Figures 2, 3
2-Input NAND with both inputs inverted	NC7SZ58	Figure 9
2-Input OR	NC7SZ58	Figure 9
2-Input OR with inverted input	NC7SZ57	Figures 2, 3
2-Input OR with both inputs inverted	NC7SZ58	Figure 6
2-Input NOR	NC7SZ57	Figure 4
2-Input NOR with inverted input	NC7SZ58	Figures 7, 8
2-Input NOR with both inputs inverted	NC7SZ57	Figure 1
2-Input XOR	NC7SZ58	Figure 10
2-Input XNOR	NC7SZ57	Figure 5

Logic Configurations NC7SZ57

Figure 1 through Figure 5 show the logical functions that can be implemented using the NC7SZ57. The diagrams show the DeMorgan's equivalent logic duals for a given 2-input function. Next to the logical implementation is the board level physical implementation of how the pins of the function should be connected.



Logic Configurations NC7SZ58

Figure 6 through Figure 10 show the logical functions that can be implemented using the NC7SZ58. The diagrams show the DeMorgan's equivalent logic duals for a given 2-input function. Next to the logical implementation is the board level physical implementation of how the pins of the function should be connected.

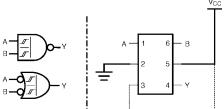


FIGURE 6. 2-Input NAND Gate

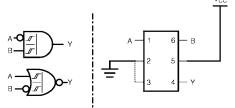


FIGURE 7. 2-Input AND with Inverted A Input

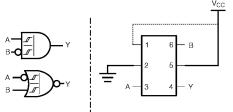


FIGURE 8. 2-Input AND with Inverted B Input

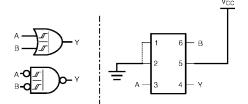


FIGURE 9. 2-Input OR Gate

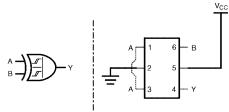


FIGURE 10. 2-Input XOR Gate

Absolute Maximum Ratings(Note 1)

Supply Voltage (V_{CC}) -0.5V to +7.0V DC Input Voltage (V_{IN}) -0.5V to +7.0V

DC Output Voltage (V_{OUT}) -0.5V to +7.0V

DC Input Diode Current (I_{IK})

 $@V_{IN} \le 0.5V$ -50 mA

DC Output Diode Current (I_{OK})

@ V_{IN} ≤ −0.5V −50 mA C Output Source/Sink Current (I_{OUT}) ±50 mA

DC Output Source/Sink Current (I_{OUT}) ± 50 mA DC V_{CC} or Ground Current (I_{CC} / I_{GND}) ± 50 mA

Storage Temperature Range (T_{STG}) -65° C to +150 $^{\circ}$ C Max Junction Temperature under Bias (T_{J}) 150 $^{\circ}$ C

Lead Temperature (T_L)

(Soldering, 10 seconds) 260°C

Power Dissipation (P_D) @+85°C

SC70-6 180 mW

Recommended Operating Conditions

Supply Voltage Operating (V_{CC}) 1.65V to 5.5V

Supply Voltage Data Retention (V_{CC}) 1.5V to 5.5V

 $\begin{array}{ll} \text{Input Voltage (V}_{\text{IN}}) & \text{0V to 5.5V} \\ \text{Output Voltage (V}_{\text{OUT}}) & \text{0V to V}_{\text{CC}} \end{array}$

Operating Temperature (T_A) $$-40^{\circ}C$$ to +85°C Thermal Resistance (θ_{JA})

SC70-6 350°C/W

±50 mA
+150°C
150°C
<l

ations

DC Electrical Characteristics

Symbol	Parameter	v _{cc}		T _A = +25°C	;	T _A = -40°	C to +85°C	Units	Conditions	
Symbol	Parameter	(V)	Min	Тур	Max	Min	Max	Units	Co	naitions
V _P	Positive Threshold Voltage	1.65	0.6	0.99	1.4	0.6	1.4			
		2.3	1.0	1.39	1.8	1.0	1.8			
		3.0	1.3	1.77	2.2	1.3	2.2	V		
		4.5	1.9	2.49	3.1	1.9	3.1			
		5.5	2.2	2.95	3.6	2.2	3.6			
V _N	Negative Threshold Voltage	1.65	0.2	0.50	0.9	0.2	0.9			
		2.3	0.4	0.75	1.15	0.4	1.15			
		3.0	0.6	0.99	1.5	0.6	1.5	V		
		4.5	1.0	1.43	2.0	1.0	2.0			
		5.5	1.2	1.70	2.3	1.2	2.3			
V _H	Hysteresis Voltage	1.65	0.15	0.48	0.9	0.15	0.9			
		2.3	0.25	0.64	1.1	0.25	1.1			
		3.0	0.4	0.78	1.2	0.4	1.2	V		
		4.5	0.6	1.06	1.5	0.6	1.5			
		5.5	0.7	1.25	1.7	0.7	1.7			
V _{OH}	HIGH Level Output Voltage	1.65	1.55	1.65		1.55				
		2.3	2.2	2.3		2.2		V	$V_{IN} = V_{IH}$ or V_{IL}	$I_{OH} = -100 \mu A$
		3.0	2.9	3.0		2.9		V	or V _{IL}	
		4.5	4.4	4.5		4.4				
		1.65	1.29	1.52		1.29				$I_{OH} = -4 \text{ mA}$
		2.3	1.9	2.15		1.9			$V_{\text{IN}} = V_{\text{IH}}$	$I_{OH} = -8 \text{ mA}$
		3.0	2.4	2.80		2.4		V	or V _{IL}	$I_{OH} = -16 \text{ mA}$
		3.0	2.3	3.68		2.3				$I_{OH} = -24 \text{ mA}$
		4.5	3.8	4.20		3.8				$I_{OH} = -32 \text{ mA}$
V _{OL}	LOW Level Output Voltage	1.65		0.0	0.10		0.10			
		2.3		0.0	0.10		0.10	V	$V_{IN} = V_{IH}$	$I_{OL}=100\;\mu A$
		3.0		0.0	0.10		0.10	•	or V _{IL}	
		4.5		0.0	0.10		0.10			
		1.65		0.08	0.24		0.24			I _{OL} = 4 mA
		2.3		0.10	0.3		0.3		$V_{IN}=V_{IH} \\$	$I_{OL} = 8 \text{ mA}$
		3.0		0.15	0.4		0.4	V	or V _{IL}	$I_{OL} = 16 \text{ mA}$
		3.0		0.22	0.55		0.55			$I_{OL} = 24 \text{ mA}$
		4.5		0.22	0.55		0.55			$I_{OL} = 32 \text{ mA}$
I _{IN}	Input Leakage Current	0-5.5			±0.1		±1	μΑ	$V_{IN} = 5.5V$,	GND

DC Electrical Characteristics (Continued)

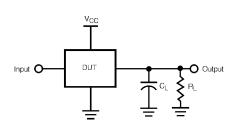
Symbol	Parameter	v _{cc}		$T_A = +25^{\circ}C$		T _A = -40°0	C to +85°C	Units	
- Cyllison	i didilictor	(V)	Min	Тур	Max	Min	Max	Omico	Conditions
l _{OFF}	Power Off Leakage Current	0.0			1		10	μΑ	V _{IN} or V _{OUT} = 5.5V
Icc	Quiescent Supply Current	1.65-5.5			1		10	μΑ	V _{IN} = 5.5V, GND

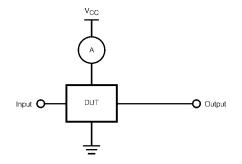
AC Electrical Characteristics

Symbol	Parameter	V _{CC}	,	T _A = +25°C	;	T _A = -40°	C to +85°C	Units	Conditions	Fig. No.
Cymbol	i diameter	(V)	Min	Тур	Max	Min	Max	Onits	Conditions	1 19. 140.
t _{PLH}	Propagation Delay In to Y	1.8 ± 0.15	3.0	8	14.0	3.0	14.5			
t_{PHL}		2.5 ± 0.2	1.5	4.9	8.0	1.5	8.5	ns	C _L = 15 pF	Figures
		3.3 ± 0.3	1.2	3.7	5.3	1.2	5.7	115	$R_L = 1 M\Omega$	11, 13
		5.0 ± 0.5	0.8	2.8	4.3	0.8	4.6			
t _{PLH}	Propagation Delay In to Y	3.3 ± 0.3	1.5	4.2	6.0	1.5	6.5	ns	C _L = 50pF	Figures
t_{PHL}		5.0 ± 0.5	1.0	3.4	4.9	1.0	5.3	115	$R_L = 500\Omega$	11, 13
C _{IN}	Input Capacitance	0		2				pF		
C _{PD}	Power Dissipation	3.3		14				pF	(Note 2)	Figure 12
	Capacitance	5.0		17				ρı		i igule 12

Note 2: C_{PD} is defined as the value of the internal equivalent capacitance which is derived from dynamic operating current consumption (I_{CCD}) at no output loading and operating at 50% duty cycle. (See Figure 12) C_{PD} is related to I_{CCD} dynamic operatic current by the expression: $I_{CCD} = (C_{PD})(V_{CC})(f_{in}) + (I_{CC}static)$.

AC Loading and Waveforms





 C_{L} includes load and stray Capacitance Input PRR = 1.0 MHz, $t_{W} = 500 \ \text{ns}$

FIGURE 11. AC Test Circuit

Input = AC Waveforms PRR = Variable; Duty Cycle = 50%

FIGURE 12. I_{CCD} Test Circuit

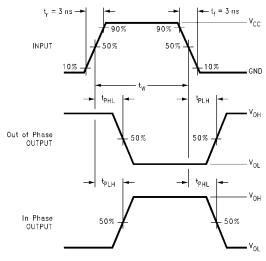


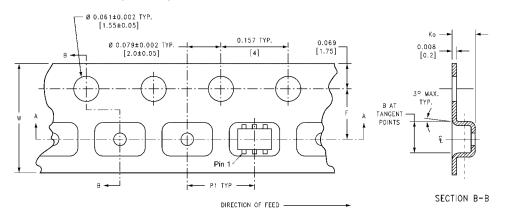
FIGURE 13. AC Waveforms

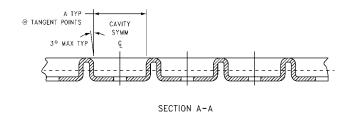
Tape and Reel Specification

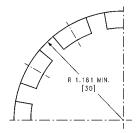
TAPE FORMAT for SC70

Package	Tape	Number	Cavity	Cover Tape
Designator	Section	Cavities	Status	Status
	Leader (Start End)	125 (typ)	Empty	Sealed
P6X	Carrier	3000	Filled	Sealed
	Trailer (Hub End)	75 (typ)	Empty	Sealed

TAPE DIMENSIONS inches (millimeters)



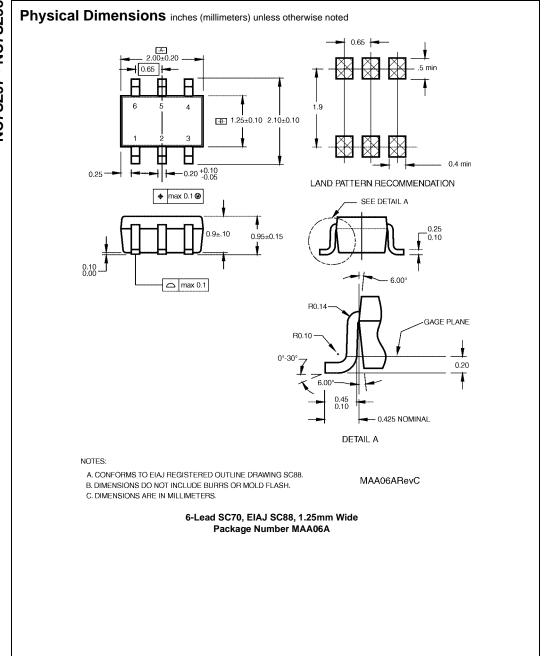




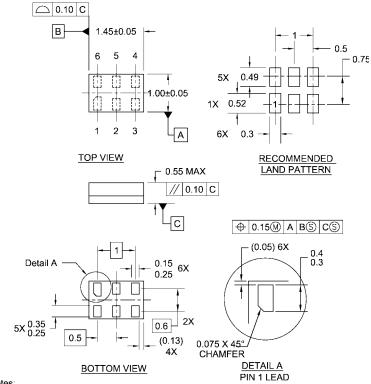
BEND RADIUS NOT TO SCALE

Package	Tape Size	DIM A	DIM B	DIM F	DIM K _o	DIM P1	DIM W
SC70-6	8 mm	0.093	0.096	0.138 ± 0.004	0.053 ± 0.004	0.157	0.315 ± 0.004
	0 111111	(2.35)	(2.45)	(3.5 ± 0.10)	(1.35 ± 0.10)	(4)	(8 ± 0.1)

Tape and Reel Specification (Continued) TAPE FORMAT for MicroPak Package Tape Number Cavity Cover Tape Designator Section Cavities Status Status Leader (Start End) 125 (typ) Empty Sealed L6X Carrier 3000 Filled Sealed Trailer (Hub End) 75 (typ) Empty Sealed 2.00-1.75±0.10 В 8.00 ^{+0.30} -0.10 3.50±0.05 1.15±0.05 В ø 0.50 ±0.05 SECTION B-B DIRECTION OF FEED SCALE:10X 0.254±0.020 ┌ 0.70±0.05 -1.60±0.05 SECTION A-A SCALE:10X **REEL DIMENSIONS** inches (millimeters) TAPE SLOT DETAIL X **DETAIL** X SCALE: 3X Tape Size В W1 W2 W3 С D N Α 7.0 0.512 0.795 0.331 + 0.059/-0.000 0.567 W1 + 0.078/-0.039 0.059 2.165 8 mm (55.00)(8.40 + 1.50 / -0.00)(W1 + 2.00/-1.00)(177.8)(1.50)(13.00)(20.20)(14.40)



Physical Dimensions inches (millimeters) unless otherwise noted (Continued)



Notes:

- 1. JEDEC PACKAGE REGISTRATION IS ANTICIPATED 2. DIMENSIONS ARE IN MILLIMETERS
- 3. DRAWING CONFORMS TO ASME Y14.5M-1994

MAC06ARevB

6-Lead MicroPak, 1.0mm Wide Package Number MAC06A

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- 2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

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